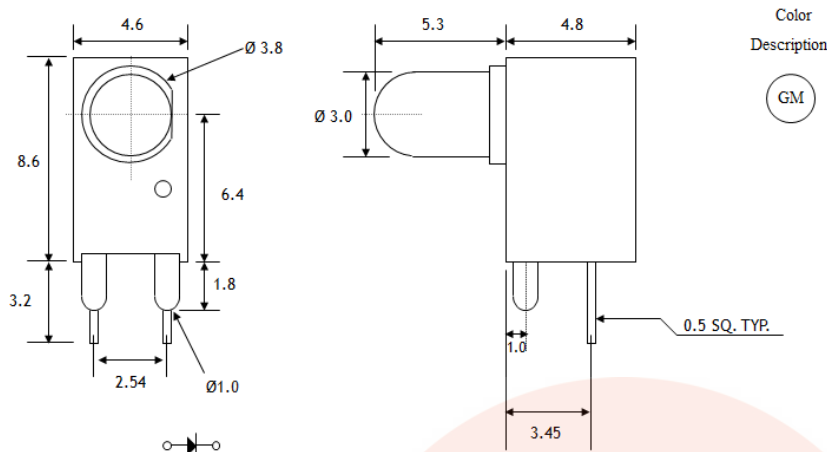


Outline Dimensions

BL-3I(GM)-1LL



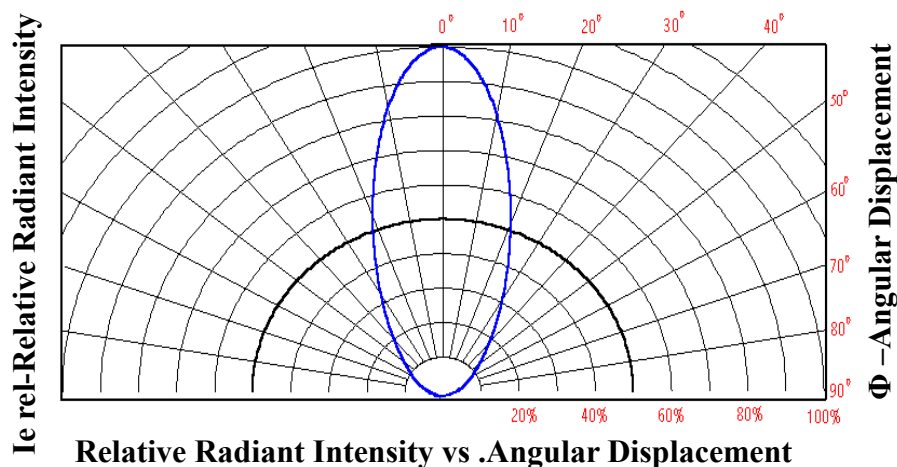
UNIT:mm

TOLERANCE is ± 0.25 mm

Features

- § forward current ≤ 30 mA
- § Wide viewing angle: 40°
- § Operating Temperature $-30 \sim 80^\circ\text{C}$
- § Storage temperature $-40 \sim 100^\circ\text{C}$
- § Junction Temperature 110°C
- § ROHS and REACH-compliant
- § Lens Color Code : White Diffused
- § Lead Frame : Ag Plating Iron Alloy
- § Resin(Mold) : Epoxy
- § Chip material: InGaN
- § Reverse Voltage: 5V
- § Pulsed Forward Current: 100mA
- § Duty 1/10 Pulse Width 0.1ms

Directive Characteristics (Ta=25°C)



Electrical-Optical Characteristics (Ta=25°C)

BL-3I(GM)-1LL

Parameter	Symbol	Value			Unit	Test condition
		Min.	Typ.	Max.		
Forward Voltage	Vf	2.8	3.2	3.8	V	If=20mA
Luminous intensity	Iv	3700	7500		mcd	If=20mA
Wavelength	λd	520		535	nm	If=20mA
Reverse Current	Ir			10	μA	Vr=5V
Viewing angle	2 θ 1/2		40		Deg	If=20mA

▲ 1.Luminous intensity (IV) $\pm 10\%$, Forward Voltage (VF) $\pm 0.1V$, Wavelength (λd) $\pm 0.5nm$

2.IS standard testing

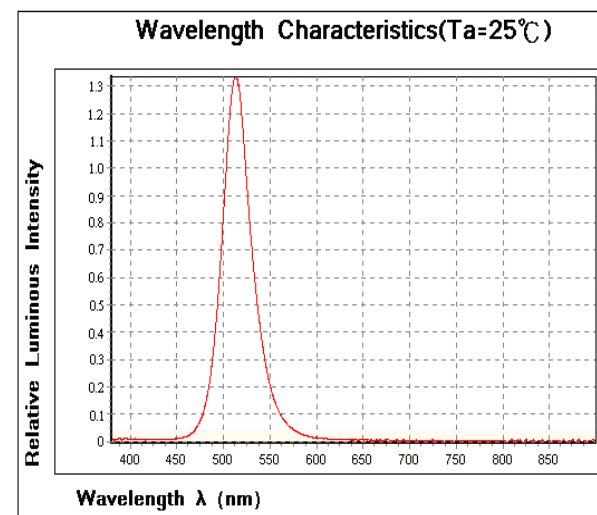
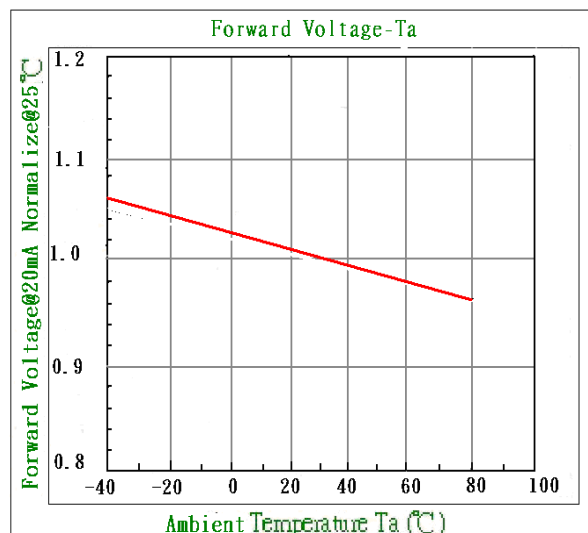
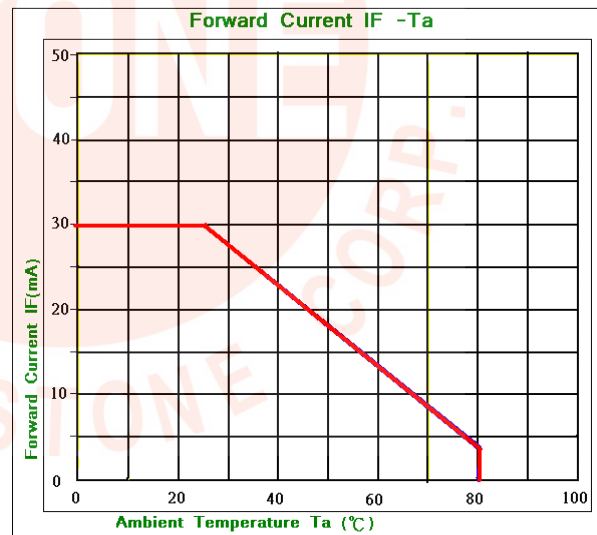
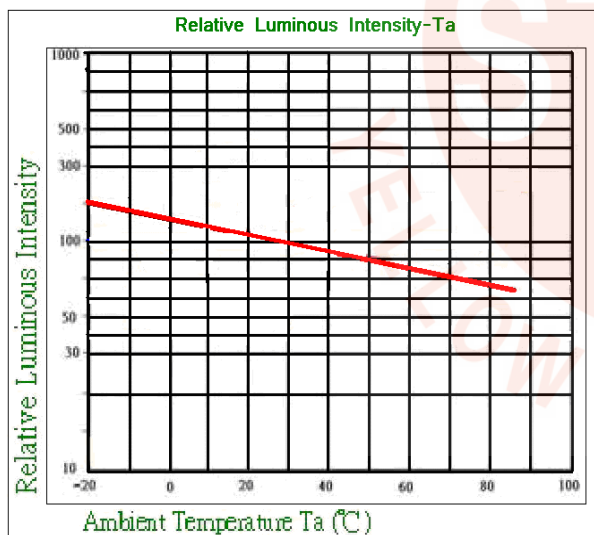
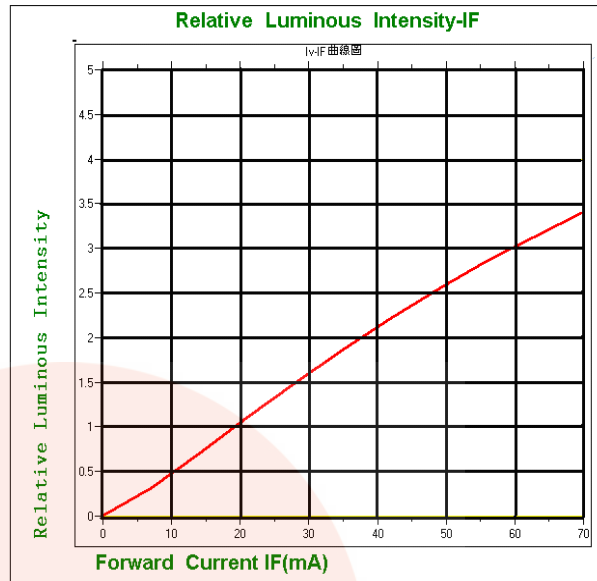
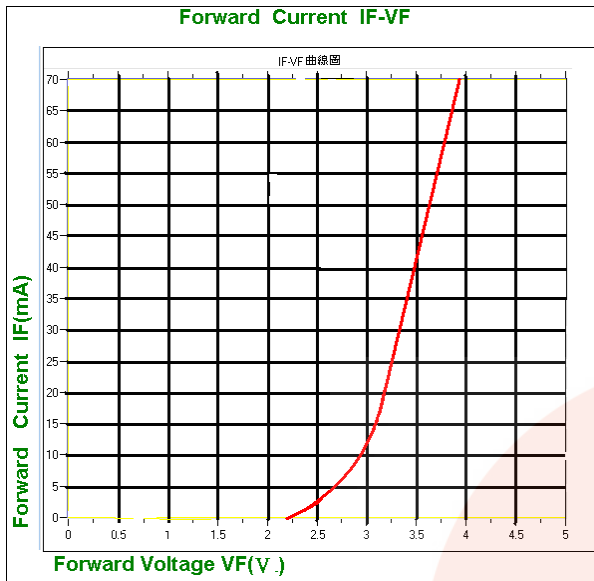
Range of bins

Bin	Bin0	Bin1	Bin2	Bin3	Bin4	Bin5	Bin6
IV	1-3	3-6	6-9	9-13	13-20	20-30	30-45
Bin	Bin7	Bin8	Bin9	Bin10	Bin11	Bin12	Bin13
IV	45-70	70-90	90-120	120-160	160-210	210-270	270-350
Bin	Bin14	Bin15	Bin16	Bin17	Bin18	Bin19	Bin20
IV	350-460	460-600	600-780	780-1000	1000-1300	1300-1700	1700-2200
Bin	Bin21	Bin22	Bin23	Bin24	Bin25	Bin26	Bin27
IV	2200-2800	2800-3700	3700-4900	4900-6300	6300-8200	8200-10600	10600-13800
Bin	Bin28	Bin29	Bin30	Bin31	Bin32	Bin33	
IV	13800-18000	18000-23400	23400-30400	30400-39500	39500-51400	51400-66800	
Bin	G	H	I				
λd	520-525	525-530	530-535				

**IV Unit: mcd. λd Unit: nm

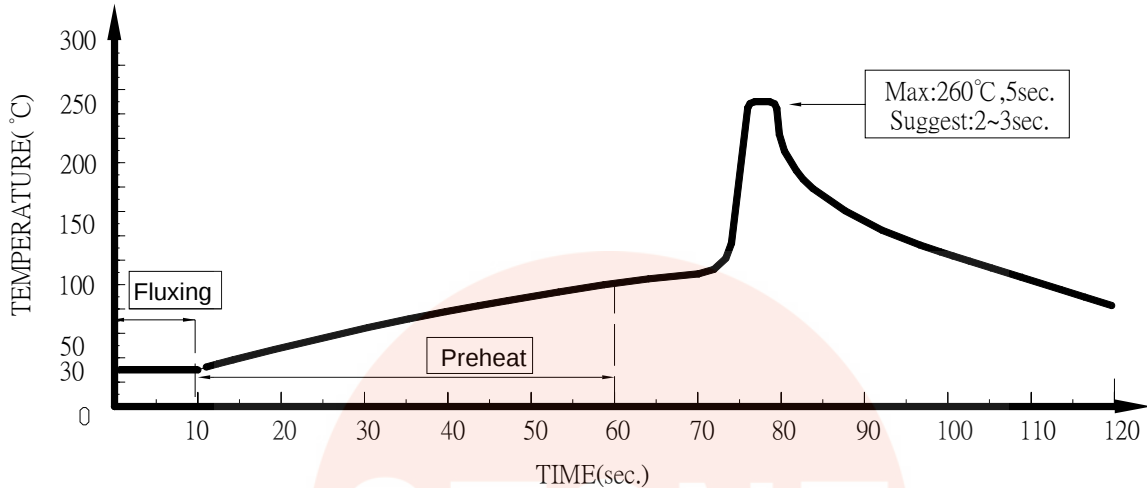
Optical Characteristics

BL-3I(GM)-1LL



Dip Soldering

BL-3I(GM)-1LL



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

● IRON Soldering

A : Max : 350°C Within 3 sec. One time only.

B : For 3mm LED without flange, if the LED epoxy lays flat on the PCB, the welding condition is 350°C within 2 seconds, one time only.

